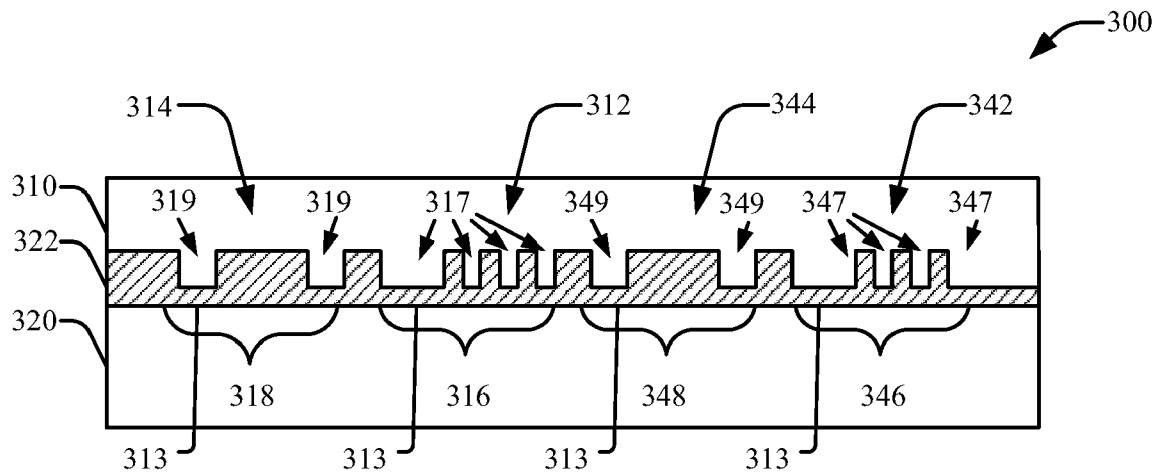




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(19) **United States**(12) **Patent Application Publication****Song et al.**(10) **Pub. No.: US 2010/0308408 A1**(43) **Pub. Date: Dec. 9, 2010**(54) **APPARATUS AND METHOD TO FABRICATE
AN ELECTRONIC DEVICE**(22) Filed: **Jun. 3, 2009****Publication Classification**(75) Inventors: **Seung-Chul Song**, Austin, TX
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B32B 3/00 (2006.01)(52) **U.S. Cl. . 257/368; 29/25.01; 428/156; 257/E21.023;
257/E27.06**Correspondence Address:
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5775 MOREHOUSE DR.
SAN DIEGO, CA 92121 (US)(57) **ABSTRACT**

An apparatus and method to fabricate an electronic device is disclosed. In a particular embodiment, an apparatus includes a template having an imprint surface. The imprint surface includes a first region having a first pattern adapted to fabricate a fin field effect transistor (FinFET) device and a second region having a second pattern adapted to fabricate a planar electronic device.

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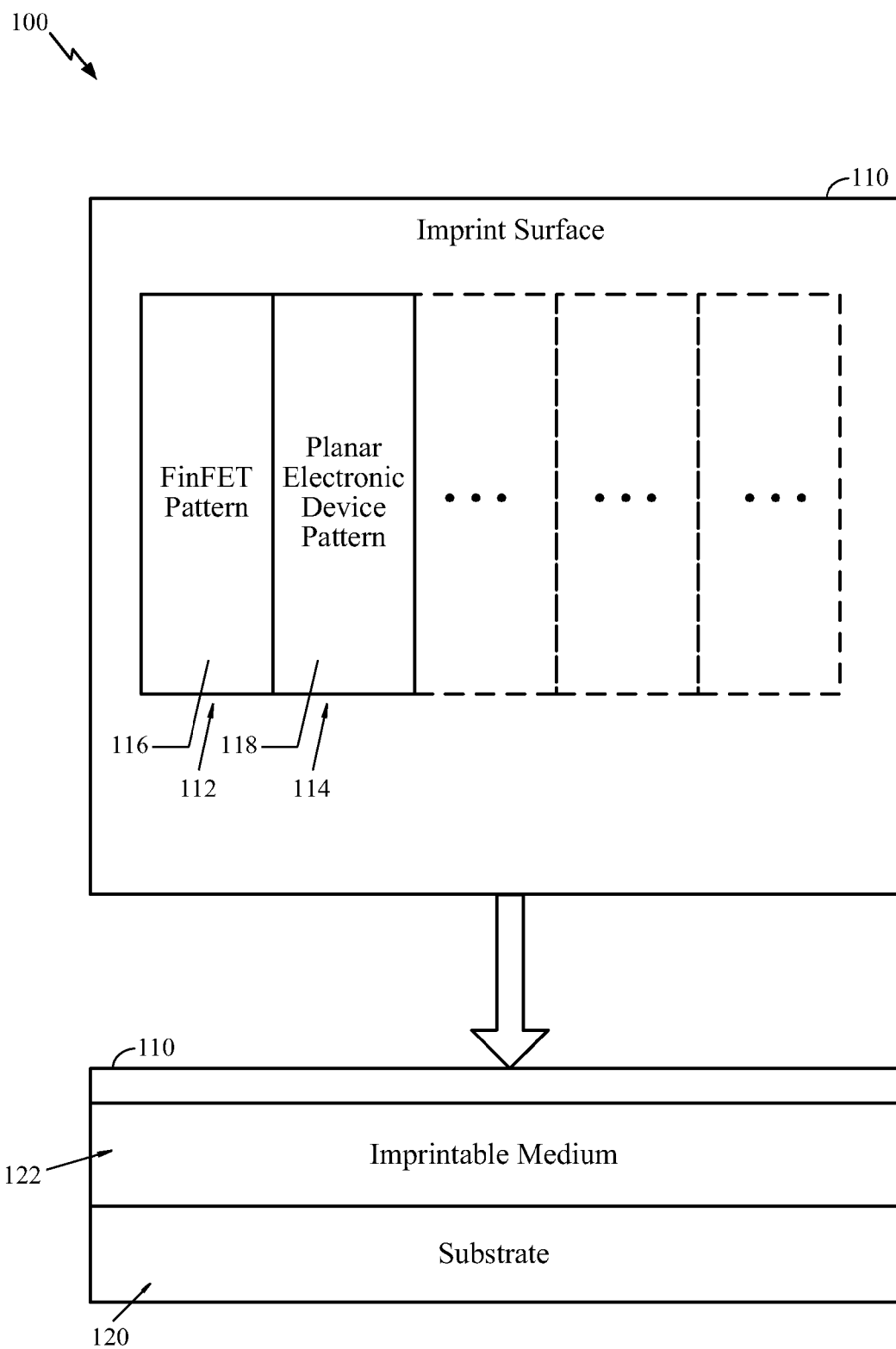


FIG. 1

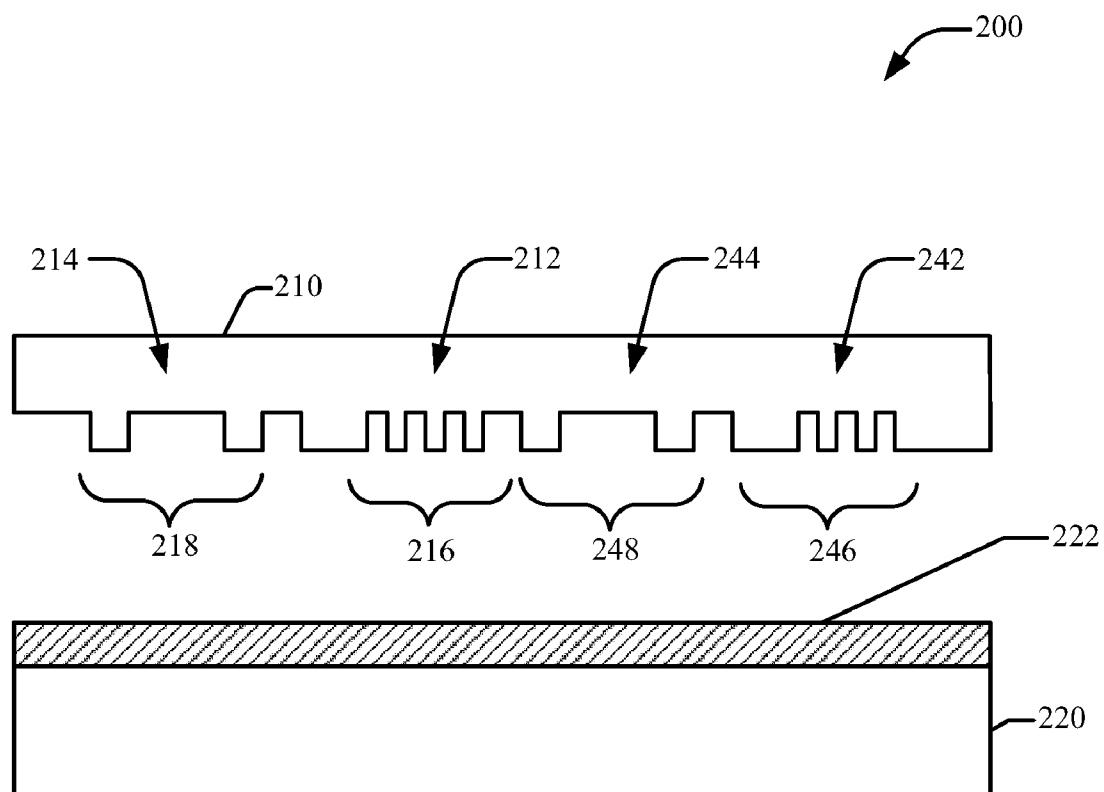


FIG. 2

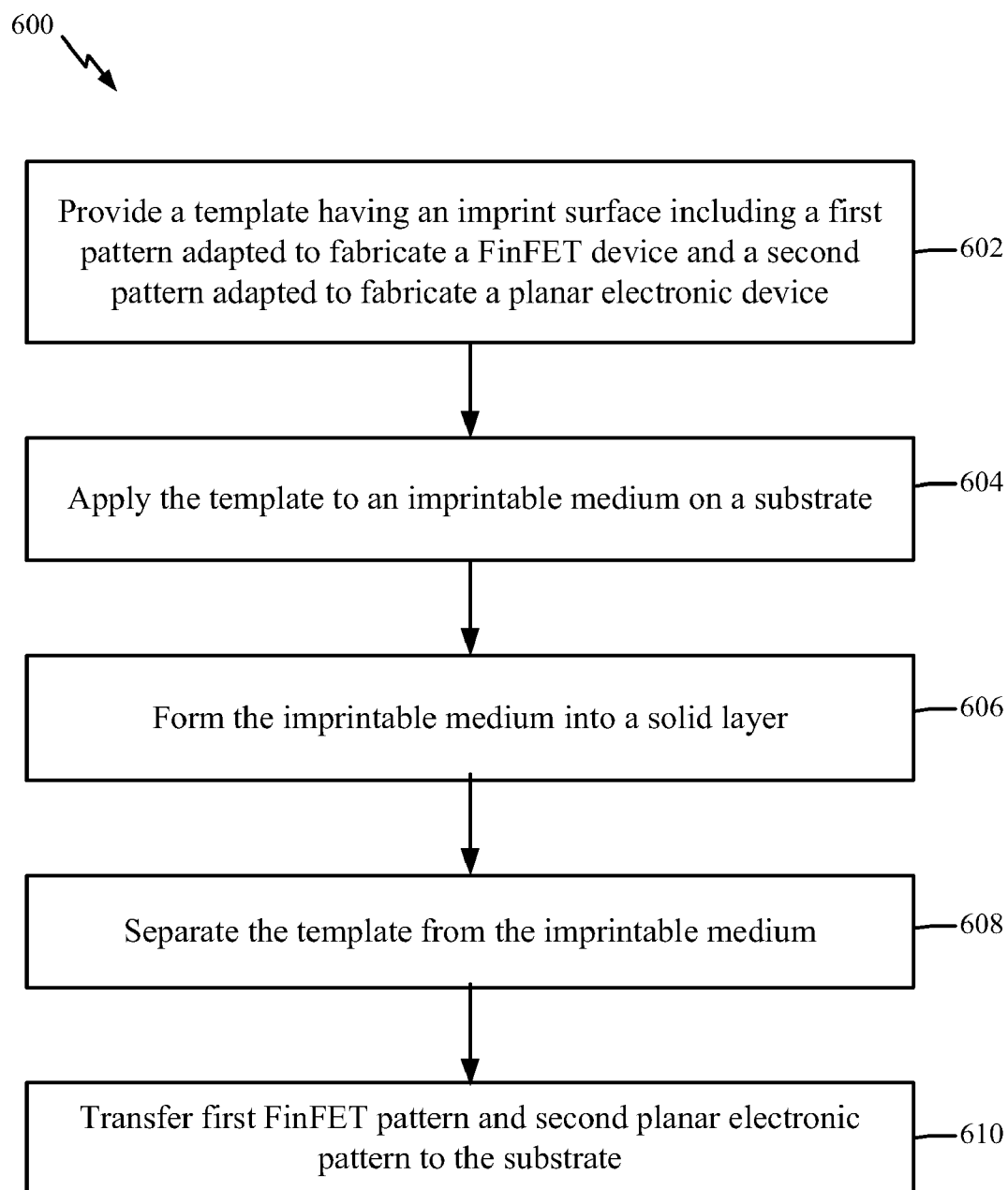


FIG. 6

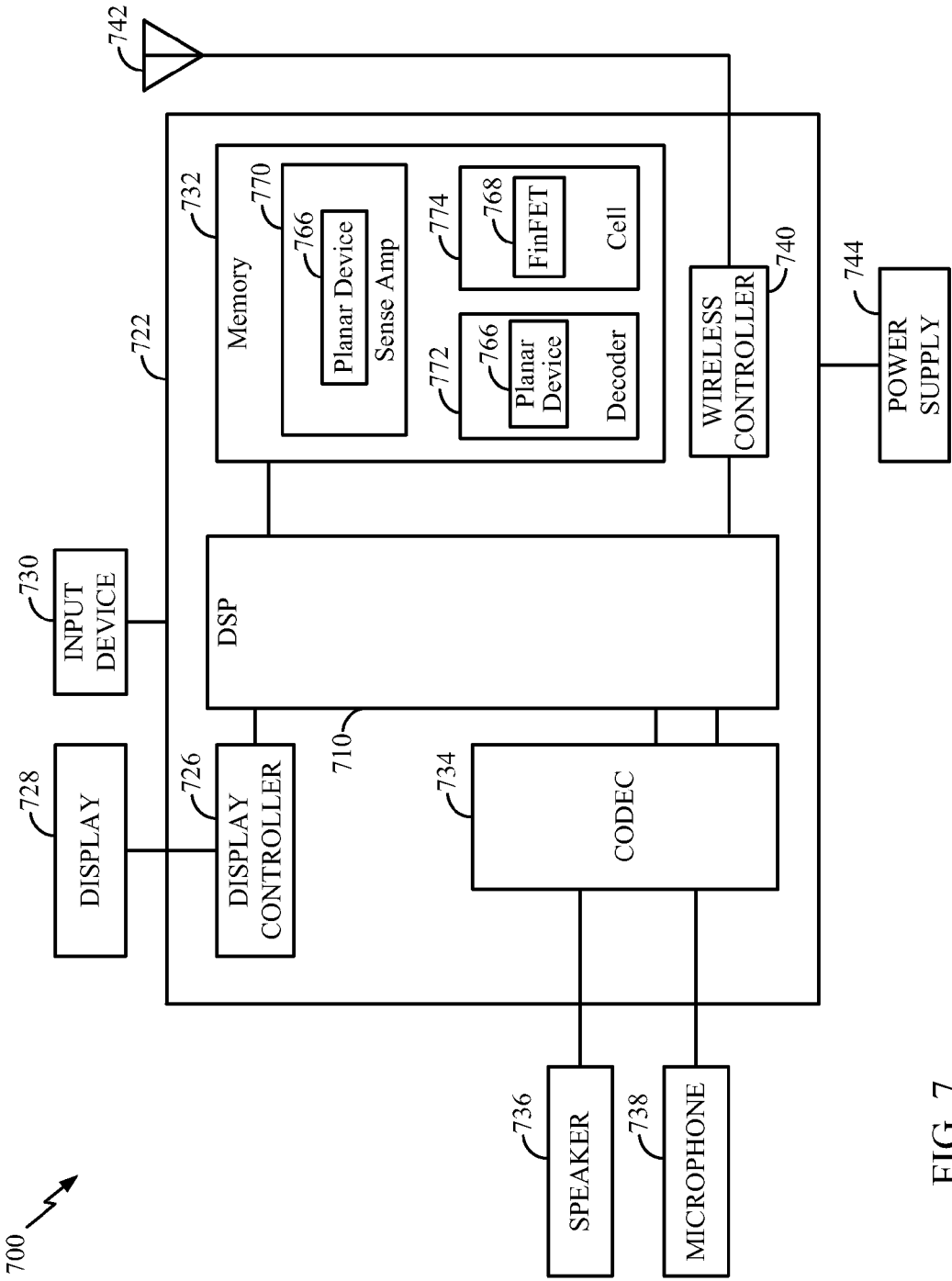


FIG. 7

APPARATUS AND METHOD TO FABRICATE AN ELECTRONIC DEVICE

FIELD

[0001] The present disclosure relates generally to devices integrating fin-type field effect transistors (FinFETs) and planar electronic devices on a common substrate and methods of forming such devices.

DESCRIPTION OF RELATED ART

[0002] Advances in technology have resulted in smaller and more powerful personal computing devices. For example, there currently exist a variety of portable personal computing devices, including wireless computing devices, such as portable wireless telephones, personal digital assistants (PDAs), and paging devices that are small, lightweight, and easily carried by users. More specifically, portable wireless telephones, such as cellular telephones and Internet Protocol (IP) telephones, can communicate voice and data packets over wireless networks. Further, many such wireless telephones include other types of devices that are incorporated therein. For example, a wireless telephone can also include a digital still camera, a digital video camera, a digital recorder, and an audio file player. Also, such wireless telephones can process executable instructions, including software applications, such as a web browser application, that can be used to access the Internet. However, power consumption of such portable devices can quickly deplete a battery and diminish a user's experience.

[0003] Reducing power consumption has led to smaller circuitry feature sizes and operating voltages within such portable devices. Reduction of feature size and operating voltages, while reducing power consumption, also increases sensitivity to noise and to manufacturing process variations. Fin-type field effect transistors (FinFETs) are low-power, high speed transistors that can be densely packed on a substrate. Unfortunately, FinFETs are not suitable for all purposes in integrated circuit designs. Different applications may involve use of different types of transistor devices.

[0004] One application may include both FinFETs and planar metal oxide semiconductor field effect transistors (MOSFETs) either on silicon on insulator (SOI) or bulk silicon substrate. However, techniques to integrate FinFETs and MOSFETs generally tend to result in large height differences between the FinFET gates and the MOSFET gates. As such, this height difference results in complex lithography and etching processes in addition to several manufacturing steps such as the use of multiple resist layers to form the FinFETs and the MOSFET devices.

SUMMARY

[0005] In a particular embodiment, an apparatus is disclosed. The apparatus includes a template having an imprint surface. The imprint surface includes a first region having a first pattern adapted to fabricate a fin field effect transistor (FinFET) device and a second region having a second pattern adapted to fabricate a planar electronic device.

[0006] In another particular embodiment, a method of fabricating an electronic device is disclosed. The method includes forming a patterned resist layer by applying a template to fluidic resist material supported by a substrate and forming the electronic device using the formed patterned resist layer. The template has an imprint surface that includes

a first region having a first pattern adapted to fabricate a fin field effect transistor (FinFET) device, and a second region having a second pattern adapted to fabricate a planar electronic device.

[0007] In another particular embodiment, a device is disclosed. The device includes a fin field effect transistor (FinFET) device and a planar electronic device. The FinFET device and the planar electronic device are located on a monolithic substrate. The FinFET device and the planar electronic device are formed by patterning a fluidic resist material with a template having an imprint surface. The imprint surface includes a first region having a first pattern adapted to fabricate a FinFET device and a second region having a second pattern adapted to fabricate a planar electronic device.

[0008] A particular advantage provided by at least one of the disclosed embodiments is that a FinFET device and a planar electronic device can be formed on a common substrate using imprint technology without the need for additional resist layers being applied to the substrate since the FinFET device and the planar electronic device are formed at substantially the same time.

[0009] Other aspects, advantages, and features of the present disclosure will become apparent after review of the entire application, including the following sections: Brief Description of the Drawings, Detailed Description, and the Claims.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] FIG. 1 is a top view of a particular illustrative embodiment of a template used in fabricating an electronic device prior to the template being pressed into an imprintable medium on a substrate;

[0011] FIG. 2 is a side view of a particular illustrative embodiment of a template used in fabricating an electronic device prior to the template being pressed into an imprintable medium on a substrate;

[0012] FIG. 3 is a side view of a particular illustrative embodiment of a template being pressed into an imprintable medium on a substrate;

[0013] FIG. 4 is a side view of a particular illustrative embodiment of a surface contour of a solid imprinted resist layer;

[0014] FIG. 5 is a side view of a particular illustrative embodiment of a pattern transferring a solid imprinted resist layer to a substrate;

[0015] FIG. 6 is a flow chart of a particular illustrative embodiment of a method of fabricating an electronic device; and

[0016] FIG. 7 is a block diagram of a portable device including a FinFET and a planar electronic device on a common substrate.

DETAILED DESCRIPTION

[0017] Referring to FIG. 1, a top view of a particular illustrative embodiment of a template used in fabricating an electronic device prior to the template being pressed into an imprintable medium on a substrate is depicted and generally designated **100**. A template **110** has an imprint surface representing a pattern to be formed on a substrate **120**. The imprint surface includes a first region **112** and a second region **114**. The first region **112** includes a first topological pattern **116** adapted to fabricate a fin field effect transistor (FinFET) device. The second region **114** includes a second topological

pattern 118 adapted to fabricate a planar electronic device. In a particular embodiment, the planar electronic device is a field effect transistor (FET) or a metal oxide semiconductor field effect transistor (MOSFET).

[0018] The first topological pattern 116 and the second topological pattern 118 are transferred to an imprintable medium 122 by pressing the template 110 into the imprintable medium 122 on the substrate 120. An example of transferring such patterns into an imprintable medium is illustrated in FIG. 2. The imprintable medium 122 can, for example, be provided as a resist layer deposited on the substrate 120. In a particular embodiment, the imprintable medium 122 is a thermosetting polymer resin, a thermoplastic polymer resin or a photo-curable liquid resist. During contact with the template 110, the imprintable medium 122 flows into pattern features defined on the template 110, and the imprintable medium 122 is thereafter hardened such that a solid layer having a contour of the template pattern is formed. Thereafter, the imprinted pattern from the imprintable medium 122 may be transferred to the substrate 120 via a pattern transfer process, such as reactive ion etching or wet chemical etching. A plurality of FinFET and planar electronic device patterns can be included on the imprint surface of the template 110, thereby concurrently forming multiple FinFET and planar electronic devices on a common substrate in subsequent processing steps. In addition, the template 110 can be used to pattern a small area of the substrate 120 by imprinting the template 110 into the imprintable medium 122, curing the imprintable medium 122 beneath the template 110, removing the template 110, stepping to an adjacent region of the substrate 120, and repeating the operation, where the first pattern 116 is adapted to fabricate a plurality of FinFET devices and the second pattern 118 is adapted to fabricate a plurality of planar electronic devices, to produce multiple regions of multiple FinFET devices and planar electronic devices.

[0019] A resolution of the features on the template imprint surface may be a limiting factor on an attainable resolution of features formed on the substrate. As such, a technique capable of very high resolution may be beneficial in forming the imprint surface pattern. The template imprint surface pattern may be formed by electron beam writing. Additionally, release characteristics of the template 110 can also be a consideration, since poor template release or sticking may cause peeling or other damage to the imprinted layer resulting in the degradation of dimensional integrity of the imprinted pattern or features. The template 110 can, for example, be treated with a surface treatment material such as a lubricant coating to form a release layer on the template 110.

[0020] Referring to FIG. 2, a side view of a particular illustrative embodiment of a template 210 that may be used in fabricating an electronic device by pressing the template 210 into an imprintable medium 222 on a substrate 220 is depicted and generally designated 200. The template 210 has an imprint surface representing a pattern to be formed on the substrate 220. In an exemplary embodiment, the template 210 is a monolithic template and has an imprint surface that includes a first region 212, a second region 214, a third region 242, and a fourth region 244. The first region 212 includes a first pattern 216 adapted to fabricate a fin field effect transistor (FinFET) device. The second region 214 includes a second pattern 218 adapted to fabricate a planar electronic device, such as a FET. The third region 242 includes a third pattern 246 adapted to fabricate another FinFET device. The fourth region 244 includes a fourth pattern 248 adapted to fabricate

another planar electronic device such as a second FET. The first pattern 216, the second pattern 218, the third pattern 246, and the fourth pattern 248 may be transferred to the substrate 220 by a process that includes pressing the template 210 into an imprintable medium, such as a resist layer 222 on the substrate 220. During contact with the template 210, the resist layer 222 flows into the pattern features defined on the template 210, and the resist layer 222 is thereafter hardened such that a solid layer having a contour of the template pattern is formed. Thereafter, the imprinted pattern from the resist layer 222 may be transferred to the substrate 220 via a pattern transfer process, such as reactive ion etching or wet chemical etching.

[0021] Referring to FIG. 3, a side view of a particular illustrative embodiment of pressing a template into an imprintable medium, such as a resist layer, is depicted and generally designated 300. A template 310 has an imprint surface representing a pattern to be formed on a substrate 320. In a particular embodiment, the template 310 may be the template 210 shown in FIG. 2. The imprint surface includes a first region 312, a second region 314, a third region 342, and a fourth region 344. The first region 312 includes a first pattern 316 adapted to fabricate a fin field effect transistor (FinFET) device. The second region 314 includes a second pattern 318 adapted to fabricate a planar electronic device such as a FET. The third region 342 includes a third pattern 346 adapted to fabricate another FinFET device. The fourth region 344 includes a fourth pattern 348 adapted to fabricate another planar electronic device such as a second FET. Pillars 317 outline the first pattern, pillars 319 outline the second pattern, pillars 347 outline the third pattern, and pillars 349 outline the fourth pattern of the template 310. The first, second, third and fourth patterns may be transferred to the substrate 320 by a process that includes pressing the template 310 into an imprintable medium, such as a resist layer 322 on the substrate 320. The template 310 is pressed into the resist layer 322 so as to form compressed regions 313. In the illustrated embodiment, the pillars 317, 319, 347 and 349 are pressed into the resist layer 322 but do not contact the surface of the underlying substrate 320. At least portions of the resist layer 322 are made flowable such that the resist layer 322 contacts portions between the pillars 317, 319, 347 and 349. As a result, the resist layer 322 substantially conforms to the shape of the first pattern 316, the second pattern 318, the third pattern 346, and the fourth pattern 348 of the template 310.

[0022] Referring to FIG. 4, a side view of a particular illustrative embodiment of a surface contour of a solid imprinted resist layer 422 is depicted and generally designated 400. Resist layer 422 is formed on a substrate 420 by forming the resist layer 422 into a solid layer, and by removal of an imprinting template (not shown). In a particular embodiment, the solid imprinted resist layer 422 is contoured according to a plurality of pillars and recesses of a template which conform to the first, second, third, and fourth patterns of the illustrative template 210 depicted in FIG. 2.

[0023] Referring to FIG. 5, a side view of a particular illustrative embodiment of a pattern transferring a solid imprinted resist layer to a substrate is depicted and generally designated 500. A pattern transfer process, such as reactive ion etching, can be used to transfer the patterns from the solid imprinted resist layer to the substrate. In a particular embodiment, the surface contour of the solid imprinted resist layer 422 depicted in FIG. 4 is transferred to a substrate 520 via a pattern transfer process, such as reactive ion etching or wet

chemical etching, thereby forming features to be used in FinFET devices **530** and planar electronic devices **540** (e.g. FET) on the substrate **520**. No additional patterned resist layer need be applied to the substrate **520** to form the features to be used in the FinFET devices **530** and the planar electronic devices **540**, which are formed at substantially the same time.

[0024] Referring to FIG. 6, a flow diagram of a particular illustrative embodiment of a method of fabricating an electronic device is depicted and generally designated **600**. At **602**, a template is provided where the template has an imprint surface including a first pattern adapted to fabricate a FinFET device and a second pattern adapted to fabricate a planar electronic device, such as a FET. As illustrative examples, the template may be the template **110** depicted in FIG. 1 or the template **210** depicted in FIG. 2. Moving to **604**, the imprint surface patterns are transferred to an imprintable medium, such as a resist layer on a substrate, by applying the template to the imprintable medium.

[0025] Continuing to **606**, the imprintable medium (e.g. resist layer) is formed into a solid layer. For example, when a thermosetting or thermoplastic polymer resin is used, the resin is heated to a temperature, such that upon contact with the template, the resin is sufficiently flowable to flow into the pattern features defined on the template. The patterned resin is then cooled. As another example, when a photo-curable liquid resist is used, the template is typically made of transparent material. In this case, after the template and resist are pressed together, the resist is cured in UV light and becomes solid.

[0026] Moving to **608**, the template is separated from the imprintable medium and a solid imprinted layer including the imprinted pattern is formed on the substrate. Continuing to **610**, the imprinted FinFET pattern and the planar electronic pattern is transferred from the imprinted resist layer (or other imprintable medium) to the substrate via a pattern transfer process, such as reactive ion etching or wet chemical etching, thereby forming features of a FinFET device and features of a planar electronic device (e.g. FET) on the substrate. In an exemplary embodiment, the planar electronic device may be a metal oxide semiconductor field effect transistor (MOS-FET). The features of the FinFET device and the planar electronic device are formed without using additional patterned resist layers. A plurality of FinFET and planar electronic device patterns can be included on the imprint surface of the template, thereby forming multiple FinFETs and planar electronic devices.

[0027] After the formation of the FinFET device and the planar electronic device, processing occurs for formation of the remaining integrated circuit structures including interconnects, contacts, wiring layers, etc. (not shown), which are typically formed above the device level. Such processing includes the formation of insulating layers and the formation of conducting layers. The insulating layers and the conducting layers are selectively etched to form the remaining integrated circuit structures.

[0028] Referring to FIG. 7, a block diagram of a particular illustrative embodiment of an electronic device, such as a wireless phone, including a FinFET and a planar electronic device on a common substrate formed by an imprint template, as described herein, is depicted and generally designated **700**. The device **700** includes a processor, such as a digital signal processor (DSP) **710**, coupled to a memory **732** which includes a FinFET device **768** and a planar electronic device **766** on a common substrate formed by an imprint template. In

an illustrative embodiment, the memory **732** includes a sense amplifier **770**, a decoder **772**, and a memory cell **774**. In particular embodiments, the planar electronic device **766** may be included within the sense amplifier **770** or the decoder **772** of the memory **732**, and the FinFET device **768** may be included within the memory cell **774**. In an illustrative example, the FinFET device **768** and the planar electronic device **766** on a common substrate formed by an imprint template includes the FinFET devices and planar electronic device structures depicted in FIG. 5 and have topological features determined using the method of FIG. 6, using the template **110** of FIG. 1 or the template **210** of FIG. 2, or any combination thereof.

[0029] FIG. 7 also shows a display controller **726** that is coupled to the digital signal processor **710** and to a display **728**. A coder/decoder (CODEC) **734** can also be coupled to the digital signal processor **710**. A speaker **736** and a microphone **738** can be coupled to the CODEC **734**.

[0030] FIG. 7 also indicates that a wireless controller **740** can be coupled to the digital signal processor **710** and to a wireless antenna **742**. In a particular embodiment, the DSP **710**, the display controller **726**, the memory **732**, the CODEC **734**, the wireless controller **740**, and the FinFET **768** and planar electronic device **766** on a common substrate formed by an imprint template are included in a system-in-package or system-on-chip **722**. In a particular embodiment, an input device **730** and a power supply **744** are coupled to the on-chip system **722**. Moreover, in a particular embodiment, as illustrated in FIG. 7, the display **728**, the input device **730**, the speaker **736**, the microphone **738**, the wireless antenna **742**, and the power supply **744** are external to the on-chip system **722**. However, each can be coupled to a component of the on-chip system **722**, such as an interface or a controller.

[0031] Those of skill would further appreciate that various illustrative logical blocks, configurations, modules, circuits, and algorithm steps described in connection with the embodiments disclosed herein may be implemented as electronic hardware, computer software executed by a processor, or combinations of both. To clearly illustrate this interchangeability of hardware and software, various illustrative components, blocks, configurations, modules, circuits, and steps have been described above generally in terms of their functionality. Whether such functionality is implemented as hardware or software that is executed by a processor depends upon the particular application and design constraints imposed on the overall system. Skilled artisans may implement the described functionality in varying ways for each particular application, but such implementation decisions should not be interpreted as causing a departure from the scope of the present disclosure.

[0032] The steps of a method or algorithm described in connection with the embodiments disclosed herein may be embodied directly in hardware, in a software module executed by a processor, or in a combination of the two. A software module may reside in random access memory (RAM), flash memory, read-only memory (ROM), programmable read-only memory (PROM), erasable programmable read-only memory (EPROM), electrically erasable programmable read-only memory (EEPROM), registers, hard disk, a removable disk, or any other form of storage medium known in the art. An exemplary storage medium is coupled to the processor such that the processor can read information from, and write information to, the storage medium. In the alternative, the storage medium may be integral to the processor. The

processor and the storage medium may reside in an application-specific integrated circuit (ASIC). The ASIC may reside in a computing device or a user terminal. In the alternative, the processor and the storage medium may reside as discrete components in a computing device or user terminal.

[0033] The previous description of the disclosed embodiments is provided to enable any person skilled in the art to make or use the disclosed embodiments. Various modifications to these embodiments will be readily apparent to those skilled in the art, and the principles defined herein may be applied to other embodiments without departing from the scope of the disclosure. Thus, the present disclosure is not intended to be limited to the embodiments shown herein but is to be accorded the widest scope possible consistent with the principles and novel features as defined by the following claims.

What is claimed is:

1. An apparatus comprising:
a template having an imprint surface, wherein the imprint surface includes a first region having a first pattern adapted to fabricate a fin field effect transistor (FinFET) device and a second region having a second pattern adapted to fabricate a planar electronic device.
2. The apparatus of claim 1, wherein the template is a monolithic template.
3. The apparatus of claim 1, wherein the FinFET device and the planar electronic device are located on a substrate.
4. The apparatus of claim 1, wherein the template is configured to impart the first pattern and the second pattern to an imprintable medium on a substrate.
5. The apparatus of claim 1, wherein the FinFET device and the planar electronic device are fabricated without using additional patterned resist layers.
6. The apparatus of claim 1, wherein the planar electronic device is a field effect transistor (FET).
7. The apparatus of claim 1, wherein the first pattern is adapted to fabricate a plurality of FinFET devices.
8. The apparatus of claim 1, wherein the second pattern is adapted to fabricate a plurality of planar electronic devices.
9. A method of fabricating an electronic device, the method comprising:
forming a patterned resist layer by applying a template to fluidic resist material supported by a substrate;
forming the electronic device using the formed patterned resist layer;
wherein the template has an imprint surface that includes a first region having a first pattern adapted to fabricate a fin field effect transistor (FinFET) device and a second region having a second pattern adapted to fabricate a planar electronic device.
10. The method of claim 9, further comprising:
forming the patterned resist layer into a solid layer; and
transferring the first pattern adapted to fabricate a FinFET device and the second pattern adapted to fabricate a planar electronic device to the substrate.

11. The method of claim 9, wherein the template is monolithic.

12. The method of claim 9, wherein the FinFET device and the planar electronic device are fabricated without applying an additional patterned resist layer to the substrate.

13. The method of claim 9, wherein the fluidic resist material comprises a thermoplastic polymer resin, a thermosetting polymer resin, or a photo curable liquid.

14. The method of claim 9, wherein the planar electronic device is a metal oxide semiconductor field effect transistor (MOSFET).

15. The method of claim 9, wherein the imprint surface includes a third region having a third pattern adapted to fabricate another FinFET device on the substrate and a fourth region having a fourth pattern adapted to fabricate another planar electronic device on the substrate.

16. A device comprising:

a fin field effect transistor (FinFET) device; and
a planar electronic device;

wherein the FinFET device and the planar electronic device are located on a monolithic substrate;

wherein the FinFET device and the planar electronic device are formed by patterning a fluidic resist material with a template having an imprint surface, the imprint surface including:

a first region having a first pattern, the first pattern adapted to fabricate the FinFET device; and

a second region having a second pattern, the second pattern adapted to fabricate the planar electronic device.

17. The device of claim 16, wherein the template is a monolithic template.

18. The device of claim 16, wherein the planar electronic device is a metal-oxide semiconductor field effect transistor (MOSFET).

19. The device of claim 16, further comprising a wireless phone that includes the FinFET device and the planar electronic device.

20. The device of claim 16, wherein the planar electronic device is included in a sense amplifier of a memory device.

21. The device of claim 20, wherein the FinFET device is included in a memory cell of the memory device.

22. The device of claim 16, wherein the planar electronic device is included in a decoder of a memory device.

23. The device of claim 22, wherein the FinFET device is included in a memory cell of the memory device.

24. The device of claim 16, further comprising a second FinFET device, wherein the first pattern is further adapted to fabricate the second FinFET device.

25. The device of claim 16, further comprising a second planar electronic device, wherein the second pattern is further adapted to fabricate the second planar electronic device.

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